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SPECIFICATION

PART NO.: LPCYN3-CY-2UCQ8AS02 7.0mm x 2.0mm SMD TYPE

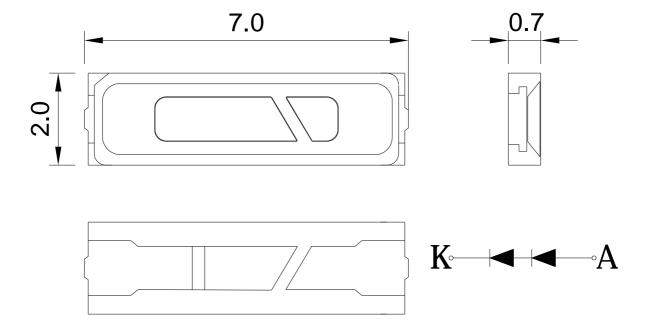




Approved by	Checked by	Prepared by	
Yue	Lian	JinHui	



Package Dimensions



Notes:

- 1. All dimensions are in mm.
- 2. The specifications, characteristics and technical data described in the datasheet are subject to change without notice.
- 3. Tolerance is ± 0.25 mm unless otherwise noted.

Description

	LED		
Part No.	Material	Emitting Color	Lens Color
LPCYN3-CY-2UCQ8AS02	InGaN/Sapphire	White	Yellow Diffused

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Absolute Maximum Ratings at Ta=25 $^{\circ}$ C

Parameter	Symbol	Rating	Unit
Power Dissipation	PD	650	mW
Reverse Voltage	VR	10	V
D.C. Forward Current	If	150	mA
Peak Current(1/10Duty Cycle,0.1ms Pulse Width.)	If(Peak)	180	mA
Operating Temperature Range	Topr.	-40 to +100	$^{\circ}\!\mathbb{C}$
Storage Temperature Range	Tstg.	-40 to +100	$^{\circ}\!\mathbb{C}$
Soldering Temperature	Tsld.	Reflow Soldering: 260°C for 10 sec Hand Soldering: 350°C for 3 sec.	
Electric Static Discharge Threshold (HBM)	ESD	1000	V

Electrical and Optical Characteristics:

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Luminous Intensity	Iv	If=150mA	36000	39000		mcd
Luminous Flux	Фу	If=150mA		115		lm
Forward Voltage	Vf	If=150mA	5.5		6.5	V
CIE Chronaticity Coordinates : X Axis	X	If=150mA		0.27		
CIE Chronaticity Coordinates : Y Axis	Y	If=150mA		0.252		
Reverse Current	Ir	Vr=5V			50	μΑ
Viewing Angle	2 \theta 1/2	If=150mA		120		deg

Notes: 1. Tolerance of Luminous Intensity is $\pm 15\%$

2. Tolerance of Forward Voltage is $\pm 0.1V$

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Specifications for Bin Grading:

Iv(mcd)				
Bin	Min.	Max.		
1	36000	37000		
2	37000	38000		
3	38000	39000		
4	39000	40000		
5	40000	41000		
6	41000	42000		
7	42000	43000		
8	43000	44000		

Specifications for Vf Group:

	Vf(V)				
Bin	Min.	Max.			
V1	5.5	5.6			
V2	5.6	5.7			
V3	5.7	5.8			
V4	5.8	5.9			
V5	5.9	6.0			
V6	6.0	6.1			
V7	6.1	6.2			
V8	6.2	6.3			
V9	6.3	6.4			
V10	6.4	6.5			

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Typical Electrical/Optical Characteristic Curves

(25°C Ambient Temperature Unless Otherwise Noted)

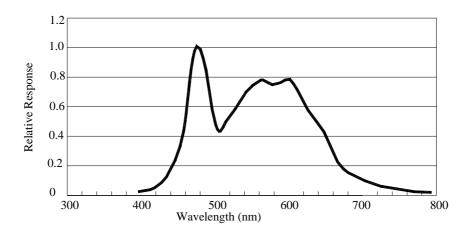
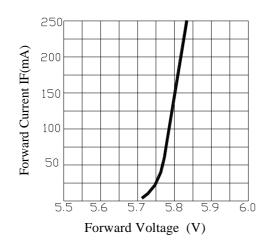
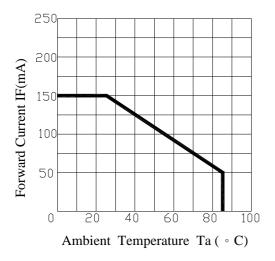


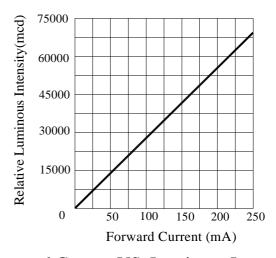
Fig.1 WHITE LED Spectrum VS. WAVELENGTH



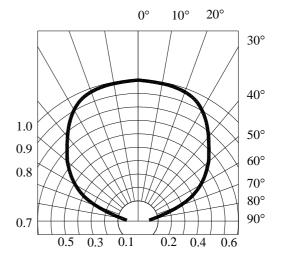
Forward Current VS. Applied Voltage



Ambient Temperature vs. Forward Current



Forward Current VS. Luminous Intensity



Radiation Diagram

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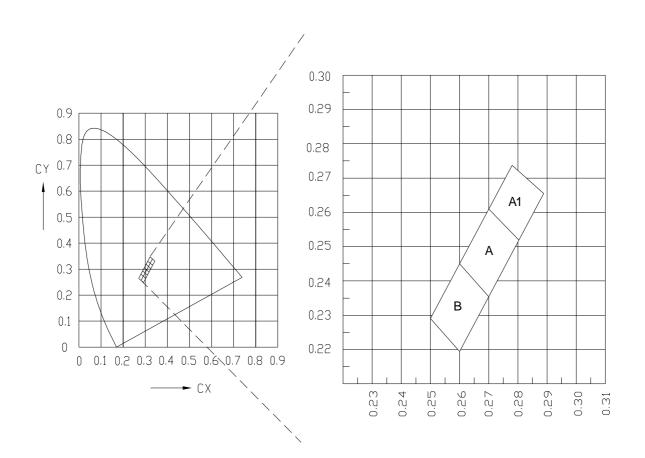
Chromaticity Coordinates Specifications for Bin Grading:

COLOR RANKS (IF=150mA.Ta=25°C)

BIN	RANK				
A 1	X	0.270	0.280	0.291	0.281
A1	Y	0.265	0.282	0.273	0.256
	X	0.260	0.270	0.281	0.271
A	Y	0.248	0.265	0.256	0.239
ъ	X	0.25	0.26	0.271	0.261
В	Y	0.231	0.248	0.239	0.222

Note: X.Y Tolerance each Bin limit is ±0.01.

Chromaticity Coordinates & Bin grading diagram:



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PRECAUTION IN USE

Storage

Recommended storage environment

Temperature: $5^{\circ}\text{C} \sim 30^{\circ}\text{C} (41^{\circ}\text{F} \sim 86^{\circ}\text{F})$

Humidity: 60% RH Max.

Moisture measures: Please refer to Moisture-sensitive label on reels package bags.

If unused LEDs remain, they should be stored in moisture proof packages, such as sealed container with packages of moisture absorbent material (silica gel). It is also recommended to return the LEDs to the original moisture proof bag and to reseal the moisture proof bag again.

Fold the opened bag firmly and keep in dry environment.

Soldering

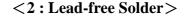
Reflow Soldering			Hand Soldering		
	Lead Solder	Lead – free Solder			
Pre-heat	120~150°C	180~200℃	Temperature	350°C Max.	
Pre-heat time	120sec. Max.	120sec. Max.	Soldering time	3sec. Max.	
Peak temperature	240°C Max.	260°C Max.		(one time only)	
Soldering time	10sec. Max.	10sec. Max.			
Condition	refer to	refer to			
	Temperature-	Temperature-			
	profile 1	profile 2			

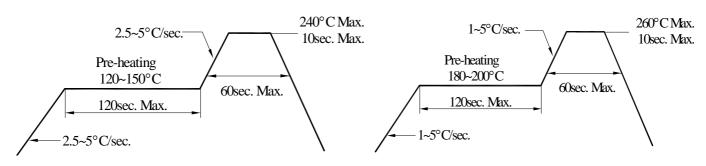
^{*}After reflow soldering rapid cooling should be avoided.

[Temperature-profile (Surface of circuit board)]

Use the conditions shown to the under figure.

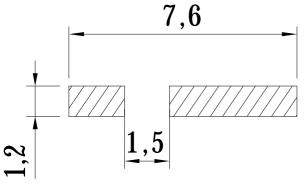
<1: Lead Solder>





[Recommended soldering pad design]

Use the following conditions shown in the figure.



Unit: mm

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Sulfur-sensitive

- I There is silver-plated metal part on the inner/outer side of the outer package.

 If exposed to the condition with corrosive gas, the silver plating surface may go bad, which will affect soldering strength and optical properties. Therefore, after opening it must be kept in a sealed container, etc.
- Materials contain sulfur component (gasket, adhesive, etc.) may have bad effects on the surface of the coating, so please do not use such materials in the product.
- In cardboard boxes and rubber, even in the atmosphere may contain minute amount of corrosive gases; In addition, the resin material may also contain halogen which has a bad effect on the surface of the coating.
- Even if the soldering installation and product assembly finished, by the effect of corrosive gas generated by relative materials of LED and external injected, the coating surface may go bad, so it is necessary to design the product taking into account the above factors.
- I If requires, it is best to use a silicone washer, but be aware that low molecular silicone may cause the product poor contact.
- Keep the product in location where has less temperature change, because moisture condensation would be generated under a condition of strong temperature change.

DISCLAIMER

- 1. Our department reserves the right(s) on the adjustment of product material mix for the specification.
- 2. The product meets our department published specification for a period of twelve (12) months from date of shipment.
- 3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
- 4. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. Our department assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
- 5. These specification sheets include materials protected under copyright of our department.

 Reproduction in any form is prohibited without obtaining our department's prior consent.
- 6. This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or life saving applications or any other application which can result in human injury or death.

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Handling of Silicone Resin LEDs

Handling Indications

During processing, mechanical stress on the surface should be minimized as much as possible. Sharp objects of all types should not be used to pierce the sealing compound

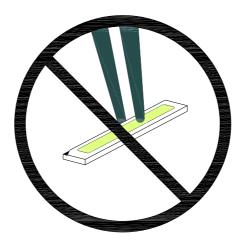


Figure 1

In general, LEDs should only be handled from the side. By the way, this also applies to LEDs without a silicone sealant, since the surface can also become scratched.

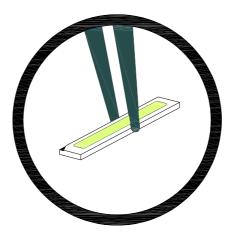


Figure 2

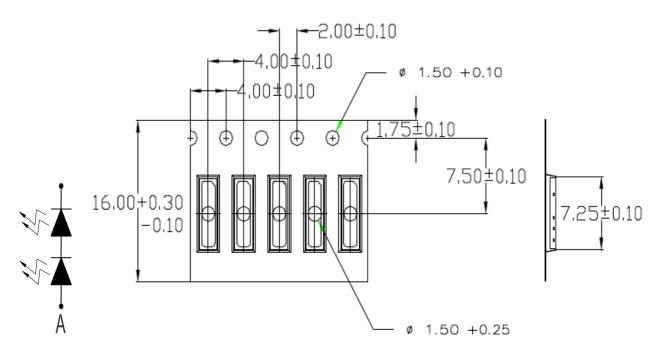
When populating boards in SMT production, there are basically no restrictions regarding the form of the pick and place nozzle, except that mechanical pressure on the surface of the resin must be prevented.

This is assured by choosing a pick and place nozzle which is larger than the LED's reflector area.

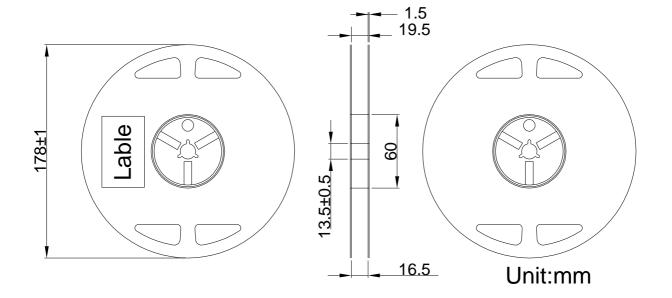
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Dimensions for Tape



Dimensions for Reel



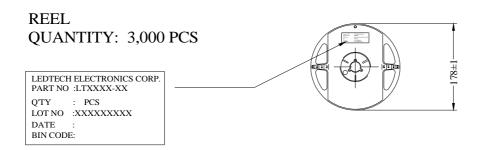
Notes:

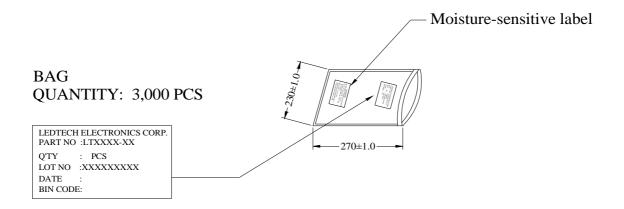
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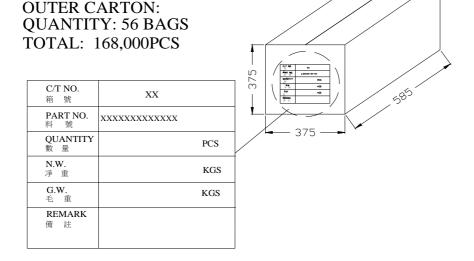
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Packing







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